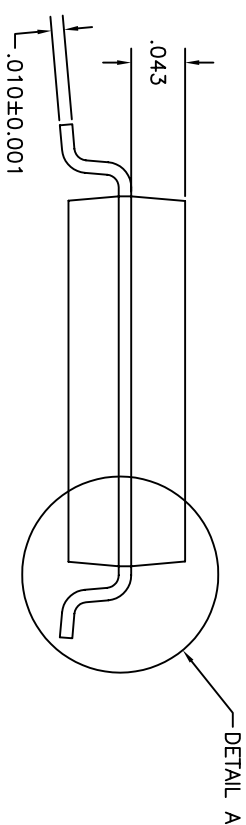
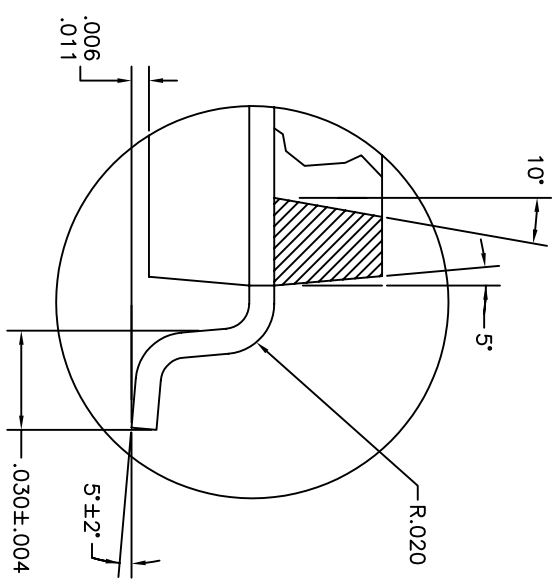
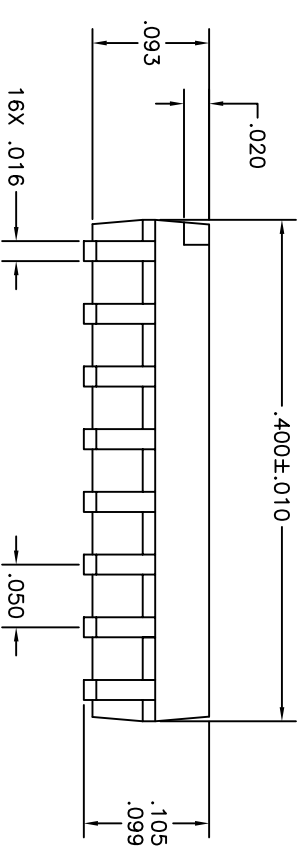
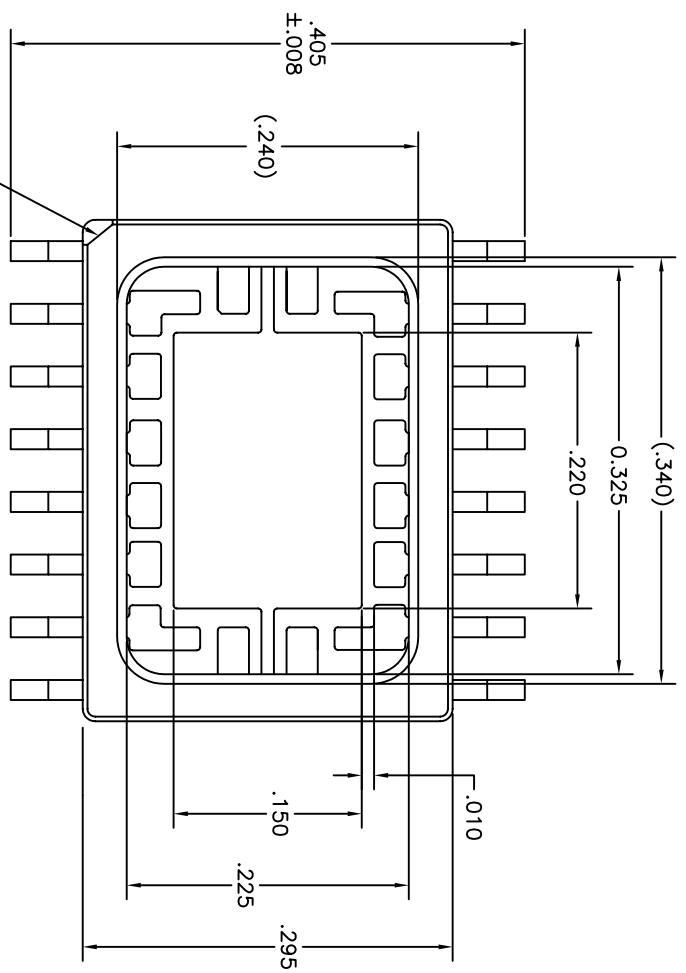


2

1

REVISIONS		APPROVED
EON NO.	DATE	DESCRIPTION
10790	11/01/06	PRODUCTION RELEASE
		D.BENAVANDO



- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE
 2. LEAD FRAME: COPPER, 194 FH.
 3. LEAD FINISH: FULL Au PLATE.
 4. DIE PAD: 0.220 X 0.150
 5. UNSPECIFIED RADIUS: R.010 MAX.
 6. JEDEC OUTLINE: MS-013



THIRD ANGLE
PROJECTION

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ARE: X.XXX ± .01 X.XXXX ± .005
ANGLES: ± 1'

DO NOT SCALE DRAWING

DRAWN	C. CRUZ	DATE	11/01/06
APP BY	P. FLASKERUD	DATE	11/01/06
CUSTOMER	---		

THIS DOCUMENT CONTAINS INFORMATION PROPRIETARY TO SEMIPAC, INC. AND IS NOT PERMITTED TO BE REPRODUCED OR TRANSMITTED IN ANY FORM OR BY ANY MEANS WITHOUT WRITTEN AUTHORITY FROM SEMIPAC, INC.

SEMPAC, INC.
 Open-Pak™ Technologies
 www.sempac.com
 588 E. WEDDELL DRIVE, SUITE 5
 SUNNYSVALE, CALIFORNIA 94089
 PHONE: (408) 400-9002 FAX: (408) 400-9006

16 Lead 300 mils
 SOIC Open-Pak

SIZE	PART NO.	REV
A	SOIC300-16-0P-01	3

SCALE NONE FILE SOIC300-16-0P-01-R3.DWG SHEET 1 OF 1

2

1